




PCN Number:	20230417002.1		PCN Date:	April 19, 2023					
Title:	Qualification of new Fab site (RFAB) using qualified Process Technology and Die Revision for select devices								
Customer Contact:	PCN Manager		Dept:	Quality Services					
Proposed 1st Ship Date:	Jul 17, 2023		Sample requests accepted until:	May 17, 2023*					
*Sample requests received after May 17, 2023 will not be supported.									
Change Type:									
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials				
<input checked="" type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification				
<input type="checkbox"/>	Test Site	<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process				
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process				
<input checked="" type="checkbox"/>	Wafer Fab Site	<input checked="" type="checkbox"/>	Wafer Fab Materials	<input checked="" type="checkbox"/>	Wafer Fab Process				
		<input type="checkbox"/>	Part number change						
PCN Details									
Description of Change:									
Texas Instruments is pleased to announce the qualification of a new fab & process technology (RFAB, Bipolar TIB) and Die Revision for select devices listed below in the product affected section.									
Current Fab Site			Additional Fab Site						
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter				
SFAB	Bipolar JIT	150 mm	RFAB	Bipolar TIB	300 mm				
The die was also changed as a result of the process change.									
Qual details are provided in the Qual Data Section.									
Reason for Change:									
These changes are part of our multiyear plan to transition products from our 150-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.									
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):									
None									
Changes to product identification resulting from this PCN:									
Fab Site Information:									
Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City						
SH-BIP-1	SHE	USA	Sherman						
RFAB	RFB	USA	Richardson						
Die Rev:									
Current		New							
Die Rev [2P]	Die Rev [2P]								
A	A								
Sample product shipping label (not actual product label)									
<div style="display: flex; justify-content: space-between; align-items: flex-start;"> <div style="width: 30%;">  <p>TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 20</p> <table border="1" style="font-size: small;"> <tr> <td>MSL 2 /260C/1 YEAR</td> <td>SEAL DT</td> </tr> <tr> <td>MSL 1 /235C/UNLIM</td> <td>03/29/04</td> </tr> </table> <p>OPT: ITEM: 39</p> <p>LBL: 5A (L)T0:1750</p> </div> <div style="width: 15%; text-align: center;">  </div> <div style="width: 15%; text-align: center;">  </div> <div style="width: 40%;"> <p>(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CS0: SHE (21L) CCO:USA (22L) AS0: MLA (23L) ACO: MYS</p> </div> </div>						MSL 2 /260C/1 YEAR	SEAL DT	MSL 1 /235C/UNLIM	03/29/04
MSL 2 /260C/1 YEAR	SEAL DT								
MSL 1 /235C/UNLIM	03/29/04								

Product Affected:

MC33063ADR

For alternate parts with similar or improved performance, please visit the product page on TI.com

Qualification Report**MC33063AD****Approve Date 13-DECEMBER-2022****Qualification Results****Data Displayed as: Number of lots / Total sample size / Total failed**

Type	#	Test Name	Condition	Duration	Qual Device: MC33063ADR	Qual Device: MC33063ADR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	3/231/0	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	3/231/0	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	3/231/0	3/231/0
HTOL	B1	Life Test	125C	1000 Hours	2/154/0	1/77/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	1/800/0	2/1600/0
ESD	E2	ESD CDM	-	1000 Volts	1/3/0	-
ESD	E2	ESD HBM	-	3000 Volts	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0

- QBS: Qual By Similarity
- Qual Device MC33063ADR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contact below or your local Field Sales Representative.

Location	E-Mail
WW Change Management Team	PCN_ww_admin_team@list.ti.com

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